

#### Is Now Part of



# ON Semiconductor®

# To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (\_), the underscore (\_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (\_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at <a href="www.onsemi.com">www.onsemi.com</a>. Please email any questions regarding the system integration to Fairchild <a href="guestions@onsemi.com">guestions@onsemi.com</a>.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer



March 2008

# FSUSB22 — Low-Power, 2-Port, High-Speed USB 2.0 (480Mbps) Switch

#### **Features**

- -40dB Off Isolation at 250MHz
- -40dB Non-adjacent Channel Crosstalk at 250MHz
- On Resistance: 4.5Ω Typical (Ron)
- -3dB Bandwidth: 750MHz
- Low-Power Consumption: 1µA Maximum
- Control Input: TTL Compatible
- Bi-directional Operation
- USB High-Speed and Full-Speed Signaling Capability

# **Applications**

 Cell Phones, PDAs, Digital Cameras, Notebook Computers

### Description

FSUSB22 is a low-power, high-bandwidth switch specially designed for applications switching high-speed USB 2.0 signals in handset and consumer applications; such as cell phone, digital camera, and notebook with hubs or controllers of limited USB I/O. The wide bandwidth (750MHz) allows signals to pass with minimum edge and phase distortion. Superior channel-to-channel crosstalk results in minimal interference. It is compatible with the USB2.0 Hi-Speed standard.

## **Ordering Information**

Part Number	Operating Temperature Range	Package	Packing Method
FSUSB22BQX	-40 to +85°C	16-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.5mm	Tape and Reel
FSUSB22QSC	-40 to +85°C	16-Lead Quarter Size Outline Package (QSOP), JEDEC MO-137, 0.150-inch Wide	Tube
FSUSB22QSCX	-40 to +85°C	16-Lead Quarter Size Outline Package (QSOP), JEDEC MO-137, 0.150-inch Wide	Tape and Reel
FSUSB22MTC	-40 to +85°C	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide	Tube
FSUSB22MTCX	-40 to +85°C	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide	Tape and Reel

All packages are lead free per JEDEC: J-STD-020B standard.

# **Logic Diagram**

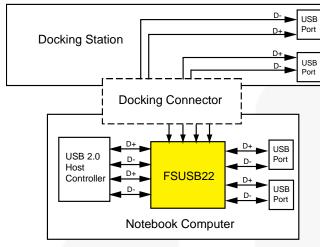


Figure 1. Logic Diagram

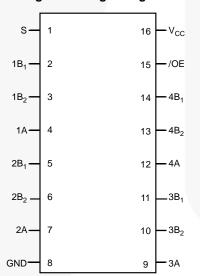


Figure 3. QSOP and TSSOP Pin Configuration

# **Analog Symbol**

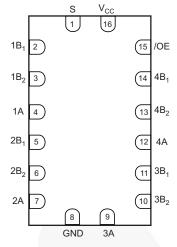


Figure 2. Analog Symbol

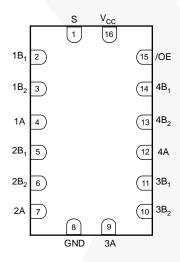


Figure 4. Pad Assignment for DQFN

# **Pin Descriptions**

Pin #	Pin Names	Description
1	S	Select Input
2,3,5,6,10,11,13,14	1B <sub>1</sub> ,1B <sub>2</sub> , 2B <sub>1</sub> ,2B <sub>2</sub> ,3B <sub>2</sub> ,3B <sub>1</sub> ,4B <sub>2</sub> ,4B <sub>1</sub>	Bus B
8	GND	Ground
4,7,9,12	1A,2A,3A,4A	Bus A
15	/OE	Bus Switch Enable
16	Vcc	Supply Voltage

#### **Truth Table**

s	OE	Function
Don't Care	HIGH	Disconnect
LOW	LOW	A=B <sub>1</sub>
HIGH	LOW	A=B <sub>2</sub>

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage	-0.5	4.6	V
Vs	DC Switch Voltage	-0.5	V <sub>CC</sub> + 0.05	V
V <sub>IN</sub>	DC Input Voltage <sup>(1)</sup>	-0.5	4.6	V
I <sub>IK</sub>	DC Input Diode Current, V <sub>IN</sub> <0V		-50	mA
l <sub>out</sub>	DC Output Sink Current		128	mA
I <sub>CC</sub> / I <sub>GND</sub>	DC V <sub>CC</sub> / GND Current		±100	mA
T <sub>STG</sub>	Storage Temperature Range	-65	+150	°C
ESD	Human Body Model, JESD22-A114		4	kV

#### Note

The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are
observed.

## **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parai	Min.	Max.	Unit	
V <sub>CC</sub>	Power Supply Operating		3.0	3.6	V
V <sub>IN</sub>	Input Voltage		0	V <sub>CC</sub>	V
Vout	Output Voltage		0	V <sub>CC</sub>	V
t <sub>r</sub> , t <sub>f</sub>	Input Disc and Fall Time	Switch Control Input <sup>(2)</sup>	0	5	ns/V
Lr, Lf	Input Rise and Fall Time Switch I/O		0	DC	115/ V
T <sub>A</sub>	Operating Temperature, Fi	-40	+85	°C	

#### Note:

2. Unused control inputs must be held HIGH or LOW. They may not float.

### **DC Electrical Characteristics**

Typical values are at  $V_{CC} = 3.0 \text{V}$  and  $T_A = 25 ^{\circ}\text{C}$ .

Symbol	Parameter	Conditions	V 00	T <sub>A</sub> =-40 to +85°C			Units
Symbol	of Farameter Conditions	V <sub>cc</sub> (V)	Min.	Тур.	Max.	Units	
V <sub>IK</sub>	Clamp Diode Voltage	I <sub>IN</sub> = -18mA	3.0			-1.2	V
$V_{IH}$	High-Level Input Voltage		3.0 to 3.6	2.0			V
$V_{IL}$	Low-Level Input Voltage		3.0 to 3.6			0.8	V
I <sub>IN</sub>	Input Leakage Current	$0 \leq V_{IN} \leq 3.6V$	3.6			±1.0	μΑ
I <sub>OFF</sub>	Off-state Leakage Current	$0 \le A, B \le V_{CC}$	3.6			±1.0	μA
В	Switch On Resistance <sup>(3)</sup>	$V_{IN} = 0.8V, I_{ON} = 8mA$	3.0		5	7	
R <sub>ON</sub>	Switch On Resistance	$V_{IN} = 3.0V, I_{ON} = 8mA$	3.0		4.5	6.5	Ω
ΔR <sub>ON</sub>	Delta R <sub>ON</sub>	$V_{IN} = 0.8V$ , $V_{IN} = 0V - 1.5$ , $I_{ON} = 8mA$	3.0		0.3		Ω
R <sub>FLAT(ON)</sub>	On Resistance Flatness <sup>(4)</sup>	I <sub>OUT</sub> = 8mA	3.0		1		Ω
Icc	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND, $I_{OUT} = 0$	3.6			1	μΑ

#### Notes:

- 3. Measured by the voltage drop between the A and B pins at the indicated current through the switch. On resistance is determined by the lower of the voltages on the A or B pins.
- 4. Flatness is defines as the difference between the maximum and the minimum value on resistance over the specified range of conditions.

### **AC Electrical Characteristics**

Typical values are at  $V_{CC}$  = 3.0V and  $T_A$  = 25°C.

Symbol	Parameter	Conditions	V <sub>cc</sub> (V)	Min.	Тур.	Max.	Units	Figure
t <sub>ON</sub>	Turn-on Time S-to-Bus B		3.0 to 3.6		4.5	6.0	ns	Figure 9 Figure 10
toff	Turn-off Time S-to-Bus B		3.0 to 3.6		2.5	4.0	ns	Figure 9 Figure 10
t <sub>PD</sub>	Propagation Delay	C <sub>L</sub> = 10pF	3.0 to 3.6		0.25		ns	Figure 14
O <sub>IRR</sub>	Non-Adjacent Off Isolation	$f = 250MHz$ , $R_L = 50\Omega$	3.0 to 3.6		-30		dB	Figure 11
X <sub>TALK</sub>	Non-Adjacent Channel Crosstalk	$f = 250MHz$ , $R_L = 50\Omega$	3.0 to 3.6		-38		dB	Figure 12
BW	-3dB Bandwidth	$R_L = 50\Omega$	3.0 to 3.6		750		MHz	Figure 13

# **USB Related AC Electrical Characteristics**

Typical values are at  $V_{CC} = 3.0V$  and  $T_A = 25$ °C.

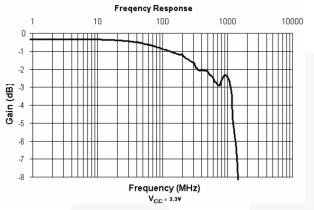
Symbol	Parameter	Conditions	V <sub>cc</sub> (V)	Min.	Тур.	Max.	Units	Figure
t <sub>SK(O)</sub>	Channel-to Channels Skew	C <sub>L</sub> = 10pF	3.0 to 3.6		0.051		pF	Figure 14 Figure 16
t <sub>SK(P)</sub>	Skew of Opposite Transition of the Same Output	C <sub>L</sub> = 10pF	3.0 to 3.6		0.020		pF	Figure 14 Figure 16
Тл	Total Jitter	$R_L = 50\Omega,$ $C_L = 10pF$ $t_R = t_F = 750ps$ at 480MPs	3.0 to 3.6		0.210			

# **Capacitance**

Typical values are at  $V_{CC}$  = 3.0V and  $T_A$  = 25°C.

Symbol	Parameter	Conditions	Тур.	Unists
C <sub>IN</sub>	Control Pin Input Capacitance	$V_{CC} = 0V$	2.5	pF
Con	A/B On Capacitance	V <sub>CC</sub> = 3.3V, /OE = 0V	12	pF
C <sub>OFF</sub>	Port B Off Capacitance	V <sub>CC</sub> and /OE = 3.3V	4.5	pF

### **Performance Characteristics**



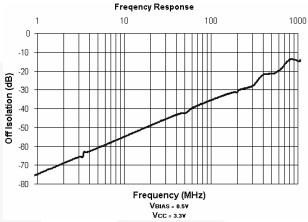
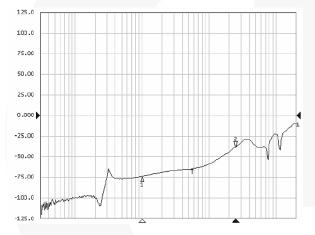


Figure 5. Gain vs. Frequency

Figure 6. Off Isolation



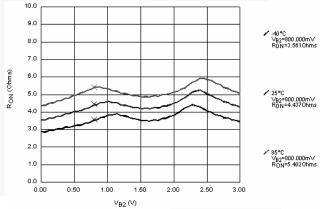
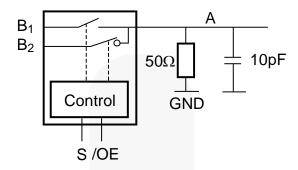


Figure 7. Crosstalk

Figure 8. RoN

# **AC Loadings and Waveforms**



Notes: Input driven by  $50\Omega$  source terminated in  $50\Omega$ . CL includes load and stray capacitance. Input PRR-1.0MHz,  $t_W = 500$ ns.

Figure 9. AC Test Circuit

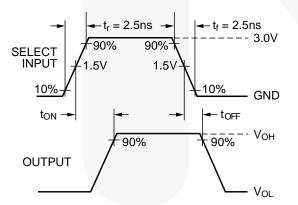


Figure 10. AC Waveforms

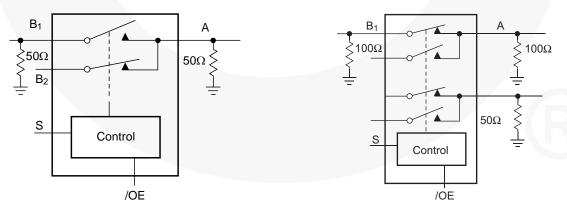
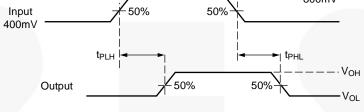
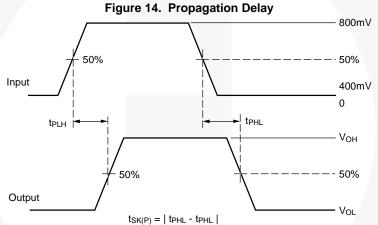


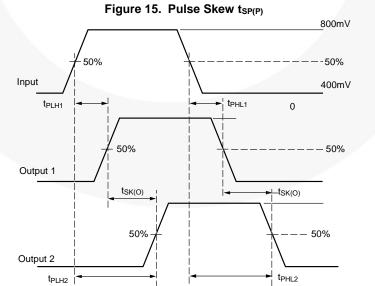
Figure 11. Off Isolation Test

Figure 12. Crosstalk Test

# AC Loadings and Waveforms B Control S Control OE Figure 13. Bandwidth Test Input 400mV

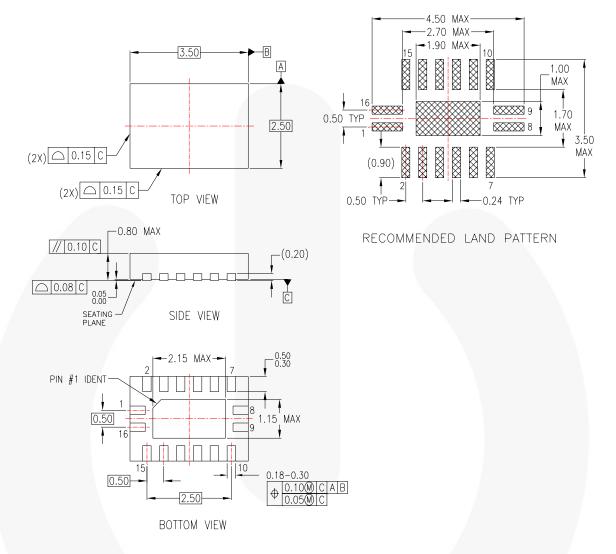






 $t_{SK(O)} = |t_{PLH1} - t_{PLH2}| \text{ or } |t_{PHL1} - t_{PHL2}|$ Figure 16. Output Skew  $t_{SK(O)}$ 

# **Physical Dimensions**



#### NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-241, VARIATION AB
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP16ErevA

Figure 17. 16-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241,2.5 x 3.5mm

Note: click here for tape and reel specifications, available at: http://www.fairchildsemi.com/products/analog/pdf/MLP16 25x35 TNR.pdf

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: http://www.fairchildsemi.com/packaging/

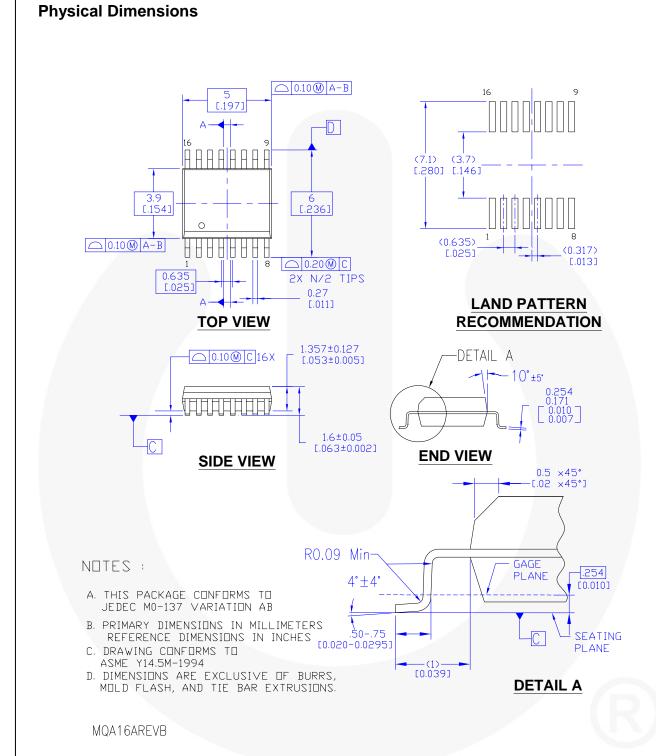
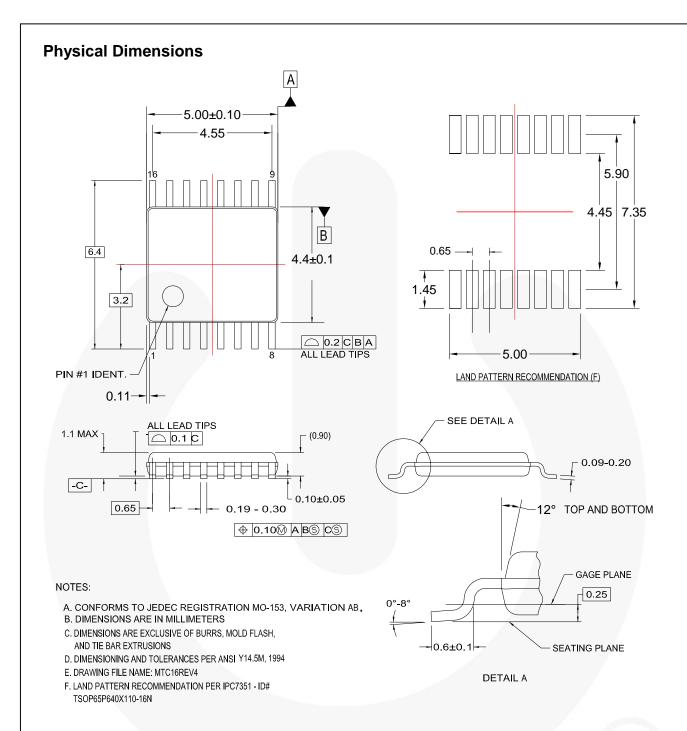


Figure 18. 16-Lead Quarter Size Outline Package (QSOP), JEDEC MO-137, 0.150-inch Wide

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: <a href="http://www.fairchildsemi.com/packaging/">http://www.fairchildsemi.com/packaging/</a>



#### MTC16rev4

Figure 19. 16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: <a href="http://www.fairchildsemi.com/packaging/">http://www.fairchildsemi.com/packaging/</a>





#### **TRADEMARKS**

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks

ACEx® Build it Now™ CorePLUS™ CorePOWER™ CROSSVOLT™ CTL TM

Current Transfer Logic™ EcoSPARK® EfficentMax™ EZSWITCH™ \*

Fairchild<sup>®</sup> Fairchild Semiconductor® FACT Quiet Series™

FACT<sup>®</sup> FAST® FastvCore™ FlashWriter®\*

FPS™ F-PFS™ FRFET®

Global Power Resources Green FPS™

Green FPS™ e-Series™ GTO™

IntelliMAX™ ISOPLANAR™ MegaBuck™ MICROCOUPLER™ MicroFET™

MicroPak™ MillerDrive™ MotionMax™ Motion-SPM™ OPTOLOGIC® OPTOPLANAR® PDP SPM™ Power-SPM™ PowerTrench®

Programmable Active Droop™

QFET<sup>®</sup> QS™

Quiet Series™ RapidConfigure™ Saving our world, 1mW at a time™

SmartMax ™

SMART START™

SPM® STEALTH™ SuperFET™ SuperSOT™-3 SuperSOT™-6 SuperSOT™-8 SupreMOS™ SyncFET\*\* SYSTEM ® GENERAL

The Power Franchise® p wer TinyBoost™

TinyBuck™ TinyLogic<sup>®</sup> TINYOPTO™ TinyPower™ TinyPWM™ TinyWire™ uSerDes™

UHC' Ultra FRFET™ UniFET™ VCX<sup>TM</sup> VisualMax™

\* EZSWITCH™ and FlashWriter® are trademarks of System General Corporation, used under license by Fairchild Semiconductor.

#### DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN, FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

#### LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- 2. A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

#### PRODUCT STATUS DEFINITIONS

#### **Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	This datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

Rev 134

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdt/Patent-Marking.pdf">www.onsemi.com/site/pdt/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and see any inability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and ex

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

# onsemi

FSUSB22MTCX FSUSB22QSCX